

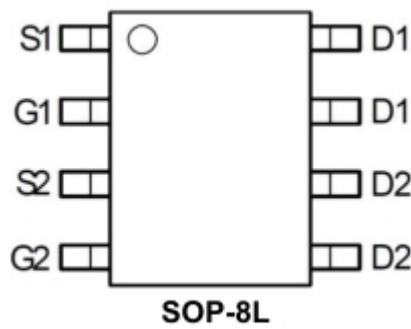
Product Summary

$V_{(BR)DSS}$	$R_{DS(on)TYP}$	I_D
30V	8.5mΩ@10V	10A
	13mΩ@4.5V	

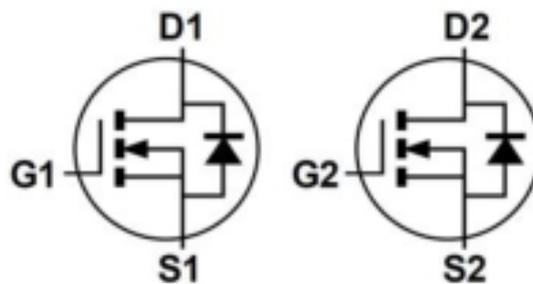
Feature

- Trench technology
- Excellent RDS(ON) with low gate charge

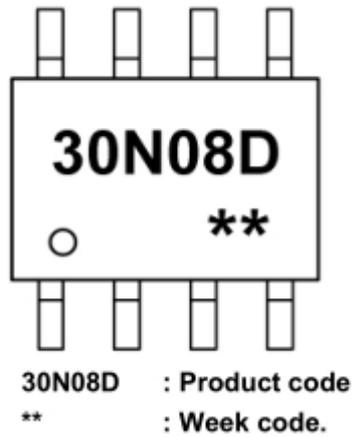
Package



Circuit diagram



Marking



Absolute maximum ratings

(T_a=25°C unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V _{DS}	30	V
Gate-Source Voltage	V _{GS}	±20	V
Continuous Drain Current	I _D	10	A
Pulsed Drain Current ¹⁾	I _{DM}	40	A
Power Dissipation	P _D	2	W
Thermal Resistance from Junction to Ambient ²⁾	R _{θJA}	62.5	°C/W
Junction Temperature	T _J	150	°C
Storage Temperature	T _{STG}	-55~ +150	°C

Electrical characteristics

($T_A=25^\circ\text{C}$, unless otherwise noted)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	$BV_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	30			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 30V, V_{GS} = 0V$			1	μA
Gate-Source Leakage	I_{GSS}	$V_{GS} = \pm 20V, V_{DS} = 0V$			± 100	μA
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	1	1.5	2.2	V
Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS} = 10V, I_D = 8A$		8.5	12	m Ω
		$V_{GS} = 4.5V, I_D = 6A$		13	17	
Dynamic Characteristics						
Input Capacitance	C_{iss}	$V_{DS} = 15V, V_{GS} = 0V,$ $f = 1MHz$	610	760	910	pF
Output Capacitance	C_{oss}		88	125	160	
Reverse Transfer Capacitance	C_{rss}		40	70	100	
Switching Times						
Turn-on Delay Time	$T_{d(on)}$	$V_{GEN} = 10V, V_{DD} = 15V,$ $R_{GEN} = 3\Omega, R_L = 1.5\Omega$		4.4		nS
Turn-on Rise Time	T_r			9		
Turn-off Delay Time	$T_{d(off)}$			17		
Turn-off Fall Time	T_f			6		
Total Gate Charge	Q_g	$V_{DS} = 15V, V_{GS} = 10V,$ $I_D = 10A$	11	14	17	pF
Gate-Source Charge	Q_{gs}			2.4		
Gate-Drain Charge	Q_{gd}			3		
Source-Drain Diode Characteristics						
Body Diode Voltage ³⁾	V_{SD}	$I_S = 1A, V_{GS} = 0V$		0.75	1	V

Notes:

1. Repetitive rating: Pulse width limited by junction temperature.
2. Surface mounted on FR4 board, $t \leq 10s$.
3. Pulse Test: Pulse Width $\leq 80\mu s$, Duty Cycle $\leq 0.5\%$.
4. Guaranteed by design, not subject to producing.

Typical Characteristics

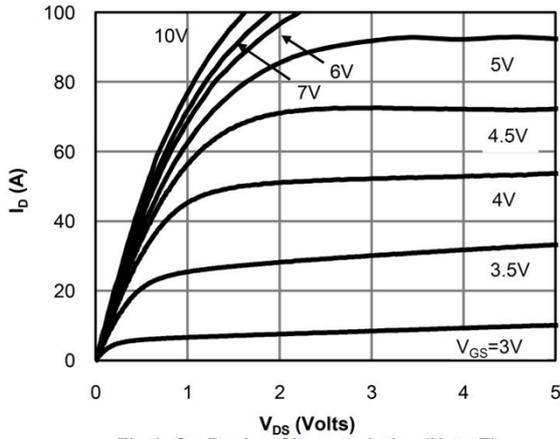


Fig 1: On-Region Characteristics (Note E)

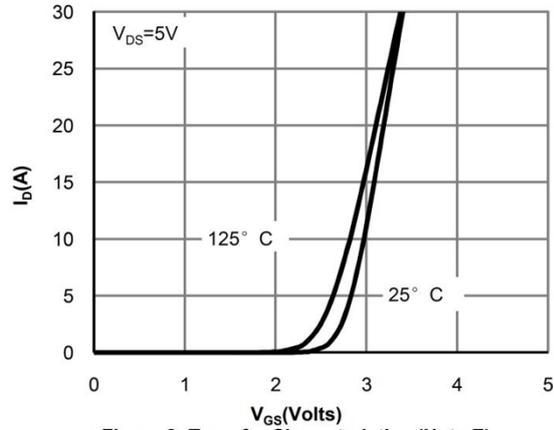


Figure 2: Transfer Characteristics (Note E)

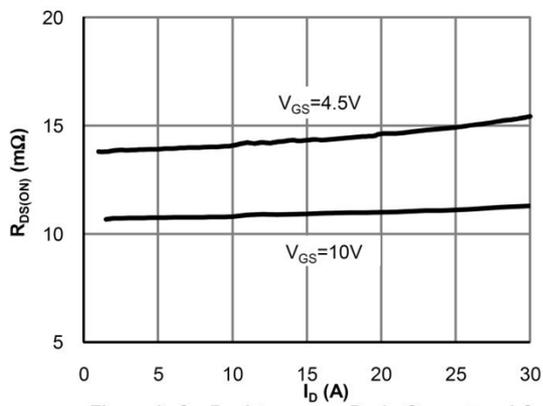


Figure 3: On-Resistance vs. Drain Current and Gate Voltage (Note E)

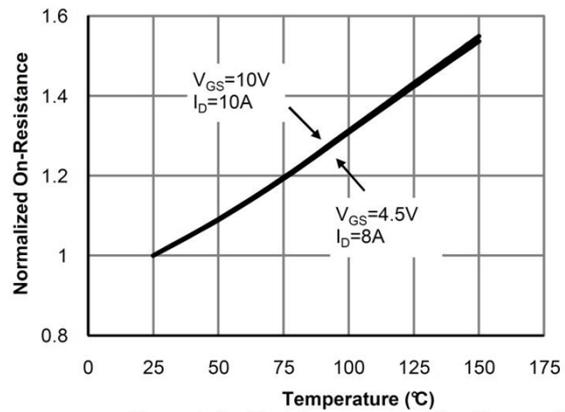


Figure 4: On-Resistance vs. Junction Temperature (Note E)

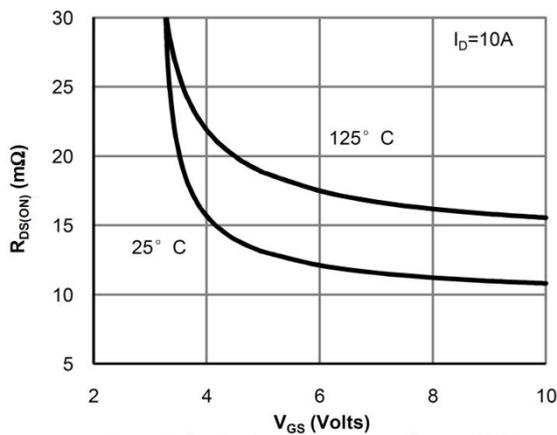


Figure 5: On-Resistance vs. Gate-Source Voltage (Note E)

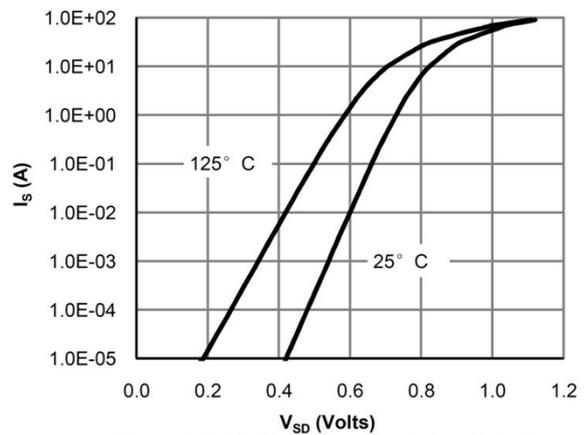


Figure 6: Body-Diode Characteristics (Note E)

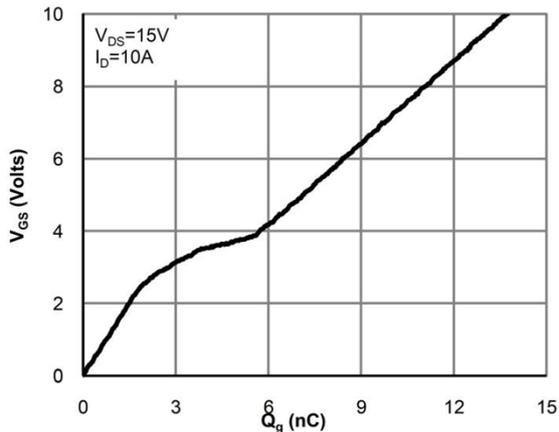


Figure 7: Gate-Charge Characteristics

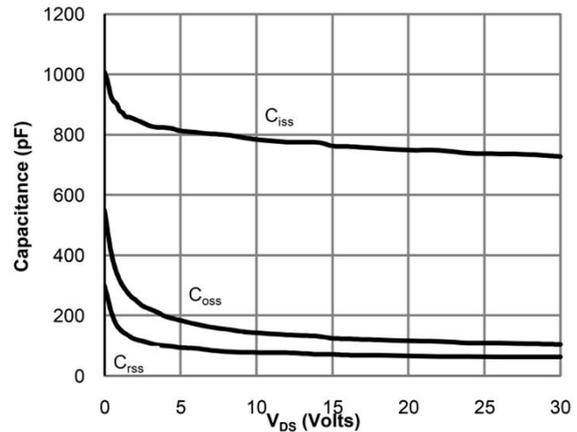


Figure 8: Capacitance Characteristics

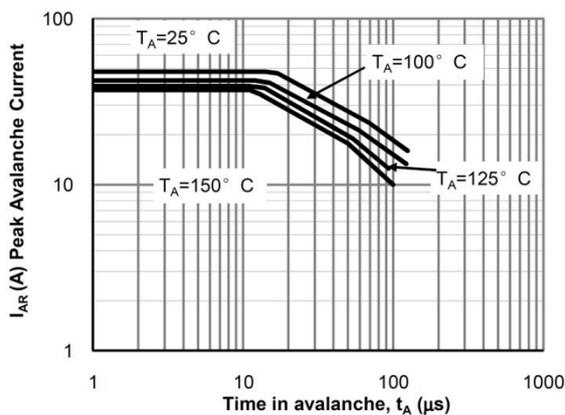


Figure 9: Single Pulse Avalanche capability (Note C)

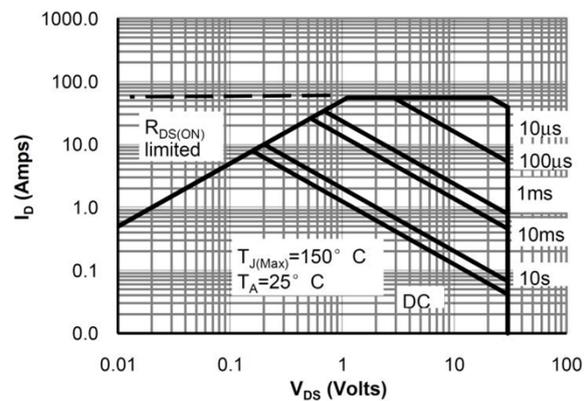


Figure 10: Maximum Forward Biased Safe Operating Area (Note F)

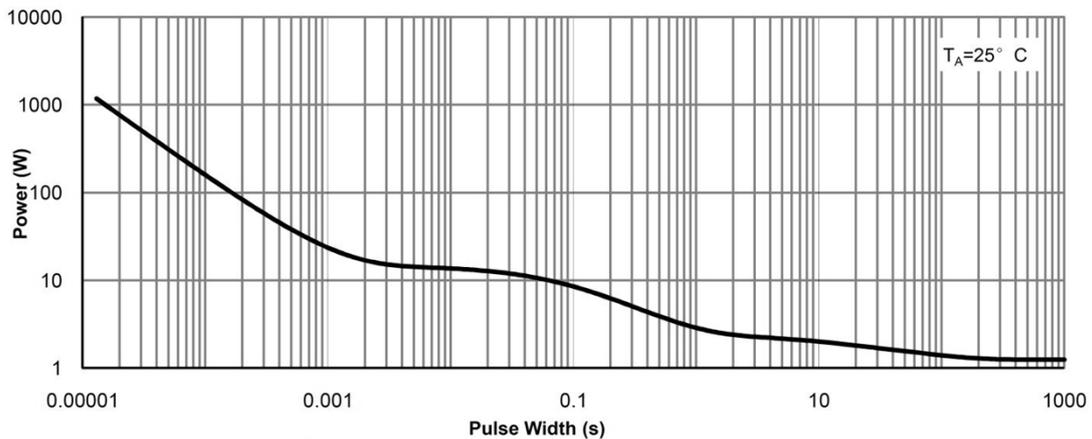
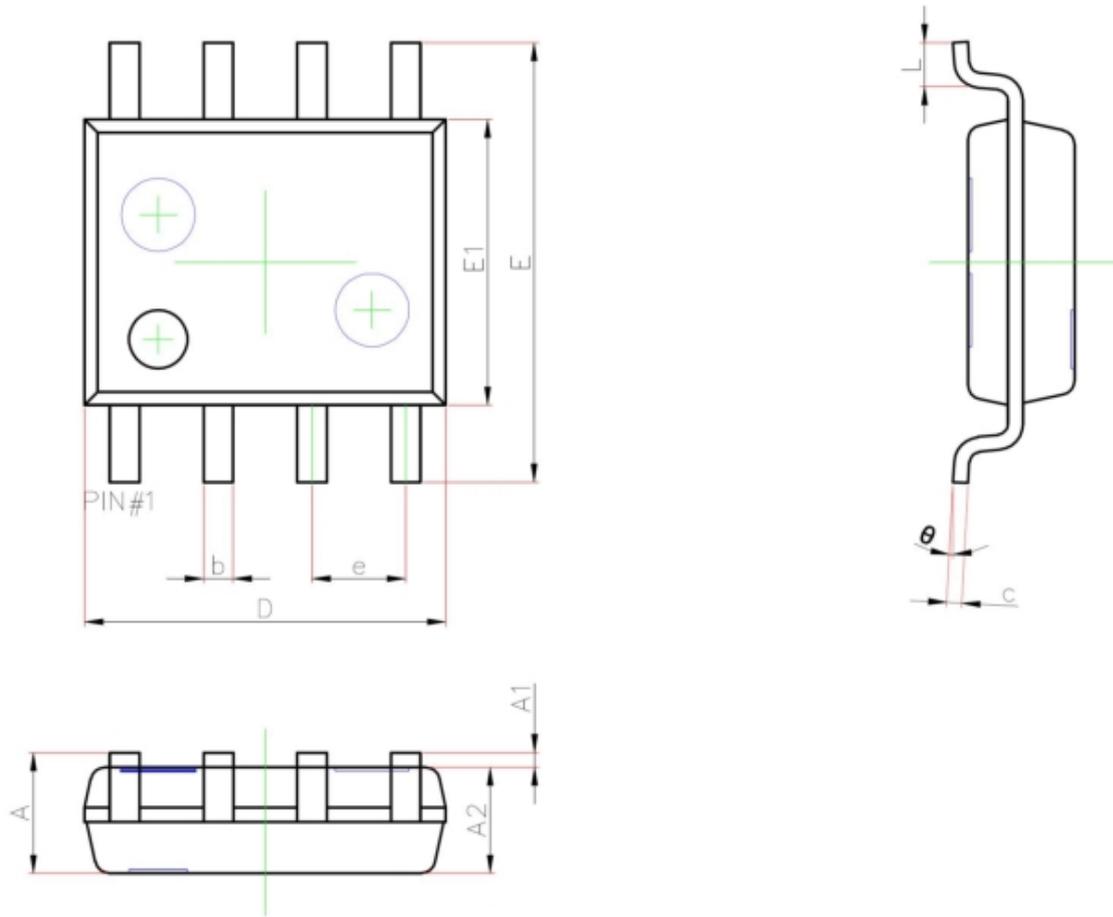


Figure 11: Single Pulse Power Rating Junction-to-Ambient (Note F)

SOP-8 Package Information



Symbol	Dimensions In Millimeters	
	Min.	Max.
A	1.35	1.75
A1	0.10	0.25
A2	1.35	1.55
b	0.33	0.51
c	0.17	0.25
D	4.80	5.00
e	1.27 REF.	
E	5.80	6.20
E1	3.80	4.00
L	0.40	1.27
θ	0°	8°